

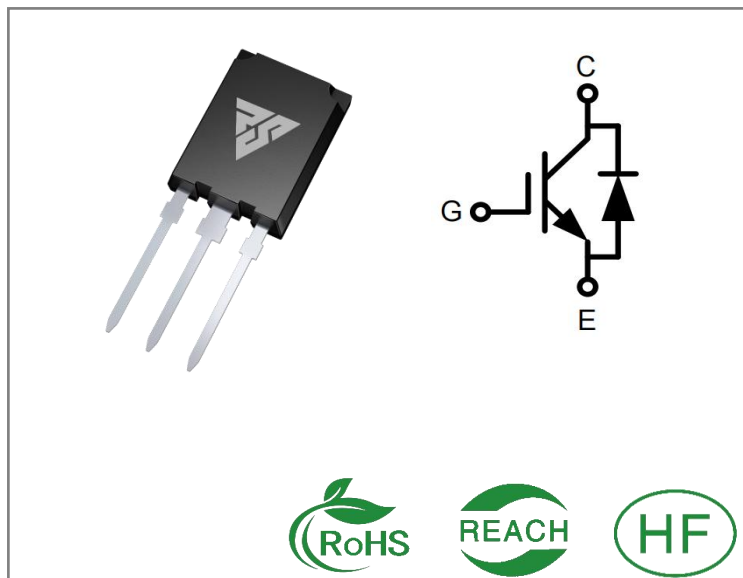
IF	V <sub>ce(sat)</sub>	VCES
120A	1.82V	1200V

**Applications:**

- Energy storage inverter
- Uninterruptible Power Supply (UPS)
- Solar Inverter

**Features:**

- 1200V trench gate/field termination process
- Very low V<sub>ce(sat)</sub>
- Low switching loss
- Positive temperature coefficient in V<sub>ce(sat)</sub>


**Ordering Information**

Part Number	Package	Marking	Packing	Qty.
RSG120N120HWP	T0-247plus-3	RSG120N120HWP	Tube	30 PCS

**Absolute Maximun Ratings** T<sub>c</sub>= 25°C unless otherwise specified

Symbol	Parameter	RSG120N120HWP	Units
VCES	Collector-Emitter Voltage	1200	V
VGES	Gate- Emitter Voltage	±20	V
IC	Continuous DC collector current TC = 100 °C	120	A
ICrm	Repetitive peak collector current tp=1 ms	360	A
Ptot	Total Power Dissipation @ TC = 25°C	1010	W
Tstg	Operating Junction and Storage Temperature Range	-40to150	°C
TL	Maximum Temperature for Soldering	260	°C

**Thermal Characteristic**

Symbol	Parameter	RSG120N120HWP	Units
R <sub>thJC</sub>	Thermal Resistance, Junction to case for IGBT	0.12	K/ W

**Electrical Characteristics** (T<sub>c</sub>=25°C unless otherwise noted)

Symbol	Parameter	Min.	Typ.	Max.	Units	Test Conditions	
Static Characteristics							
V(BR)CES	Collector-Emitter Breakdown Voltage	1200	-	--	V	V <sub>GE</sub> =0V,I <sub>CE</sub> =0.25mA	
ICES	Collector-Emitter Leakage Current	-	-	1	mA	V <sub>GE</sub> =0V, V <sub>CE</sub> =1200V	
IGES	Gate to Emitter Leakage current	-	-	200	nA	V <sub>GE</sub> =+20V, V <sub>CE</sub> =0V	
VCE(sat)	Collector-Emitter Saturation Voltage	-	1.82	2.2	V	I <sub>C</sub> =120 A	T <sub>J</sub> =25° C
	Gate Threshold Voltage	-	2.52	--	V	V <sub>GE</sub> =15 V	T <sub>J</sub> =175° C
VGE(th)	Collector-Emitter Breakdown Voltage	5.0	5.6	6.2	V	I <sub>C</sub> =2.3mA,V <sub>CE</sub> =V <sub>GE</sub>	
Gfs	Transconductance		95		S	I <sub>C</sub> =120A,V <sub>CE</sub> =20V	
Dynamic Characteristics							
Cies	Input Capacitance	-	17070	--	PF	V <sub>CE</sub> =25V, V <sub>GE</sub> =0V, f=100KHz	
Coes	Output Capacitance	-	400	--			
Cres	Reverse Transfer Capacitance	-	125	--			
Qg	Total Gate Charge		1063		uC	IC = 120A, VGE = 15 V, VCE =960 V	
Switching Characteristics							
td(ON)	Turn-on Delay Time	-	28		ns	V <sub>CE</sub> =600V, I <sub>C</sub> =120A, V <sub>GE</sub> =+/-15V, R <sub>g</sub> =3.3Ω, Inductive Load	
t <sub>r</sub>	Rise Time	-	196	--			
td(OFF)	Turn-Off Delay Time	-	150	--			
t <sub>f</sub>	Fall Time	-	70				
E <sub>on</sub>	Turn-On Switching Loss	-	17.5	--	mJ		
E <sub>off</sub>	Turn-Off Switching Loss	-	4.1	--			

**Diode Maximum Ratings** (T<sub>J</sub> = 25°C unless otherwise specified)

Symbol	Parameter	Value	Unit	Test Conditions
VRRM	Repetitive Peak Reverse Voltage	1200	V	TC = 25°C
IF	Forward Current	120	A	TC = 100°C
IFRM	Repetitive Peak Forward Surge Current	360	A	tp=1 ms

**Characteristics Values** (T<sub>C</sub>=25°C unless otherwise noted)

Symbol	Parameter	Min.	Typ.	Max.	Test Conditions	Unit
VF	Forward Voltage		2.06 1.9 1.85	2.5	IF = 120A, V <sub>GE</sub> =0V T <sub>J</sub> = 25°C IF = 120A, V <sub>GE</sub> =0V T <sub>J</sub> = 150°C IF = 120A, V <sub>GE</sub> =0V T <sub>J</sub> = 175°C	V
IRM	Peak reverse recovery current		26 62		VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 25°C VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 175°C	A
Qrr	Reverse Recovery Charge		6.2 23		VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 25°C VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 175°C	uC
trr	Reverse Recovery time		480 870		VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 25°C VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 175°C	ns
Erec	Reverse recovered energy		2.4 8.7		VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 25°C VR = 600V, IF = 120A, V <sub>GE</sub> =-15V diF/dt=500A/us T <sub>J</sub> = 175°C	mJ
R <sub>thJC</sub>	Diode Thermal Resistance, Junction		0.22			K/ W
Tvj op	Temperature under switching conditions	-40		175		°C

Typical Feature Curve

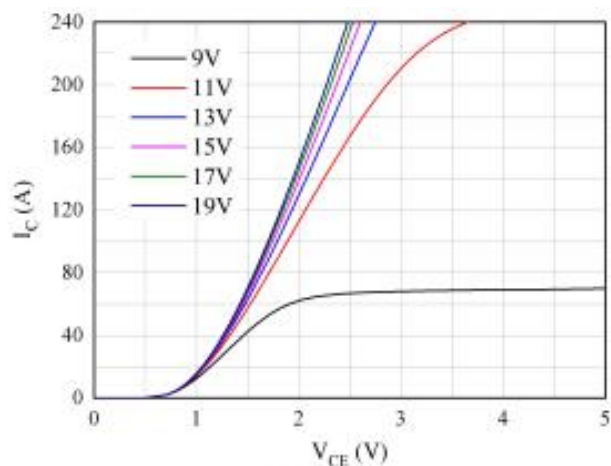


图 1. 典型输出特性 ( $T_{vj}=25^{\circ}\text{C}$ )

Figure 1. Typical output characteristics ( $T_{vj}=25^{\circ}\text{C}$ )

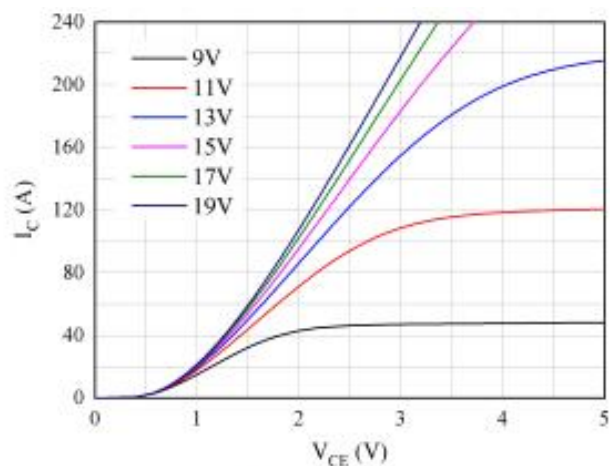


图 2. 典型输出特性 ( $T_{vj}=175^{\circ}\text{C}$ )

Figure 2. Typical output characteristics ( $T_{vj}=175^{\circ}\text{C}$ )

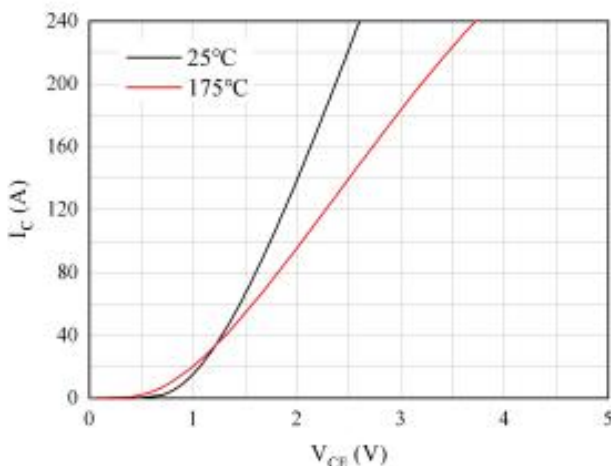


图 3. 典型输出特性 ( $V_{ge}=15\text{V}$ )

Figure 3. Typical output characteristics ( $V_{ge}=15\text{V}$ )

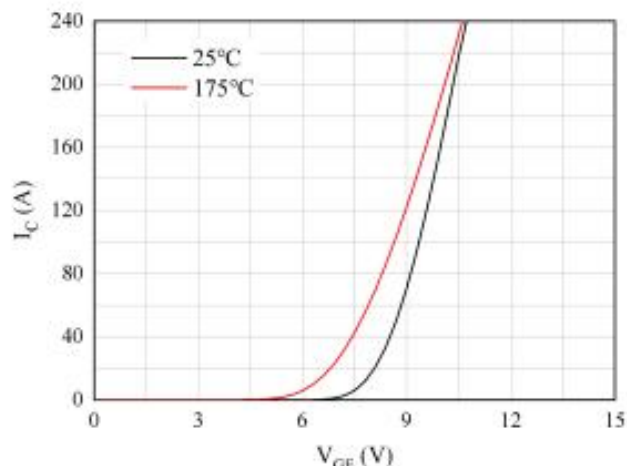


图 4. 典型传输特性 ( $V_{ce}=20\text{V}$ )

Figure 4. Typical transfer characteristic ( $V_{ce}=20\text{V}$ )

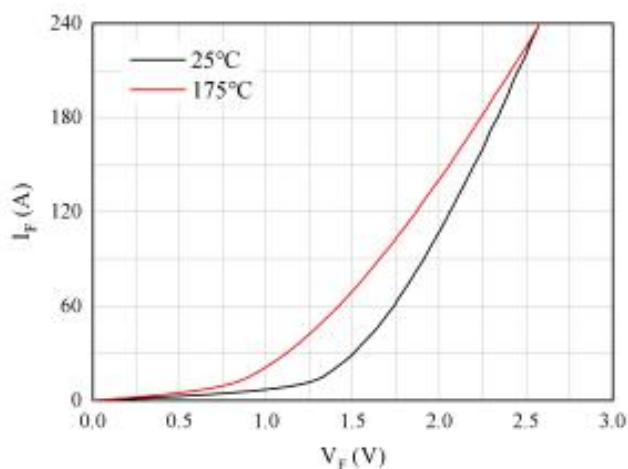


图 5. 正向偏压特性二极管

Figure 5. Forward characteristic of Diode

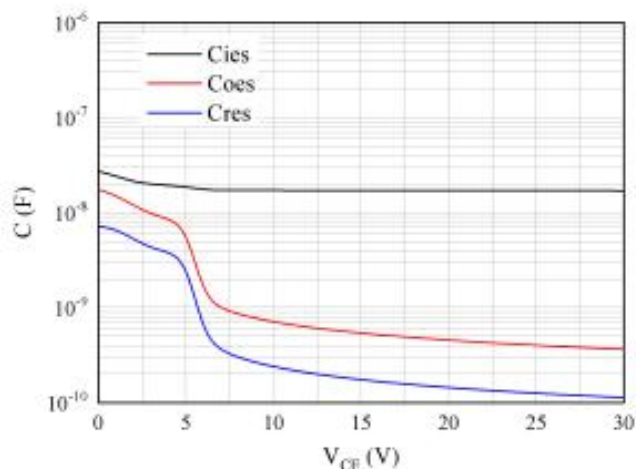


图 6. 电容特性

Figure 6. Capacitance characteristic

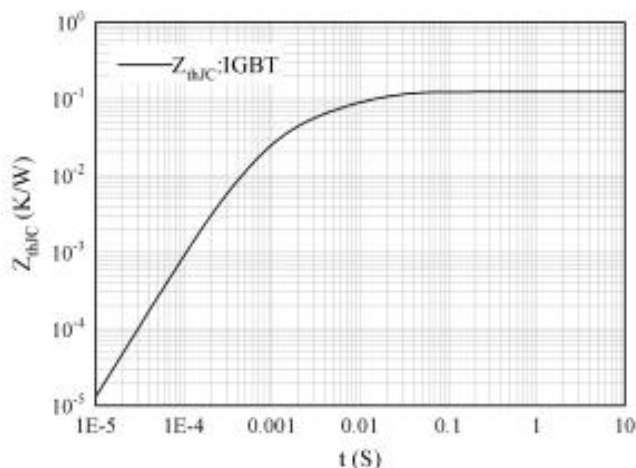


图 7. 瞬态热阻抗 IGBT

Figure 7. Transient thermal impedance IGBT,  
 $Z_{thJC}=f(t)$

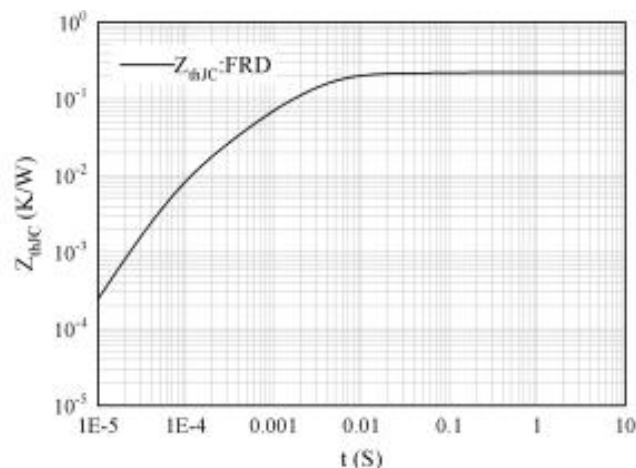


图 8. 瞬态热阻抗 FRD

Figure 8. Transient thermal impedance FRD,  
 $Z_{thJC}=f(t)$

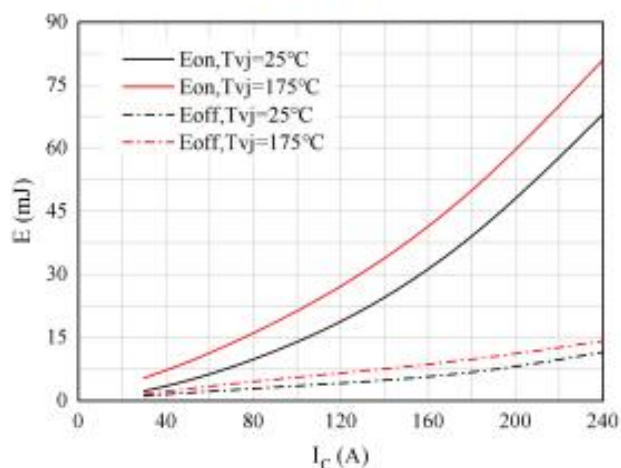


图 9. 开关损耗

Figure 9. Switching losses of IGBT  
 $V_{GE}=\pm 15V$ ,  $R_{gon}=3.3\Omega$ ,  $R_{goff}=3.3\Omega$ ,  $V_{CE}=600V$

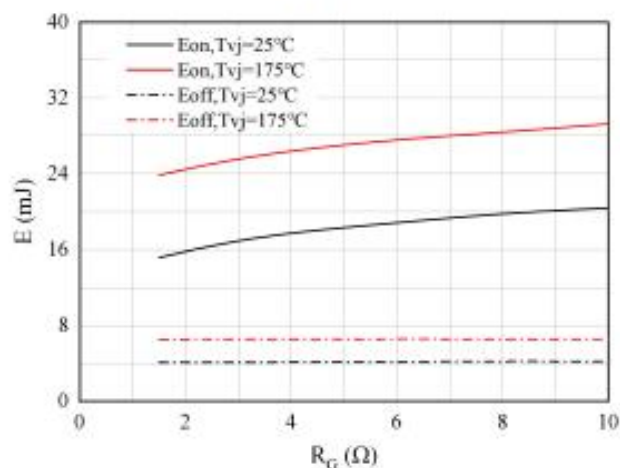


图 10. 开关损耗

Figure 10. Switching losses of IGBT  
 $V_{GE}=\pm 15V$ ,  $I_C=120A$ ,  $V_{CE}=600V$

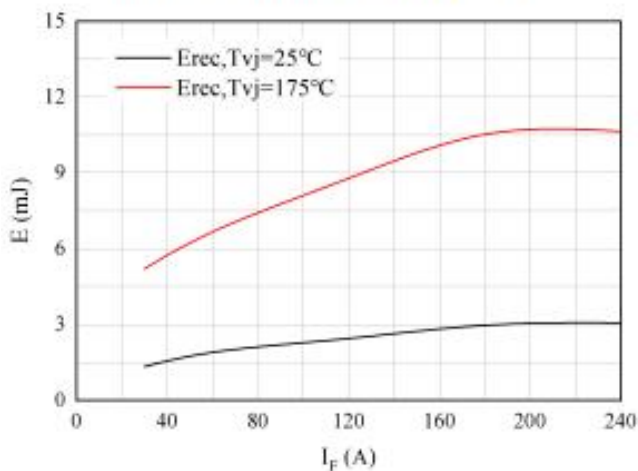


图 11. 开关损耗 二极管

Figure 11. Switching losses of Diode  
 $R_{gon}=3.3\Omega$ ,  $V_{CE}=600V$

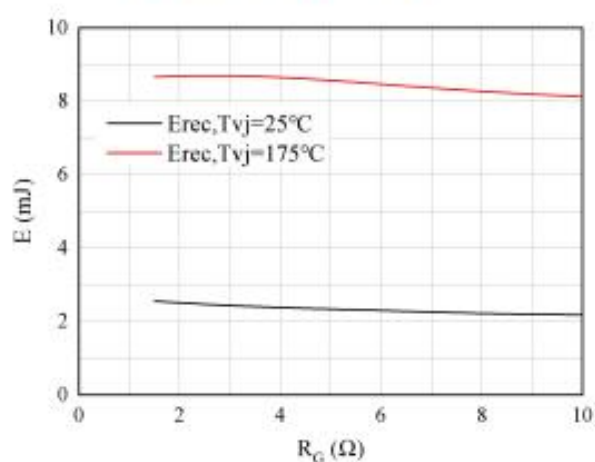
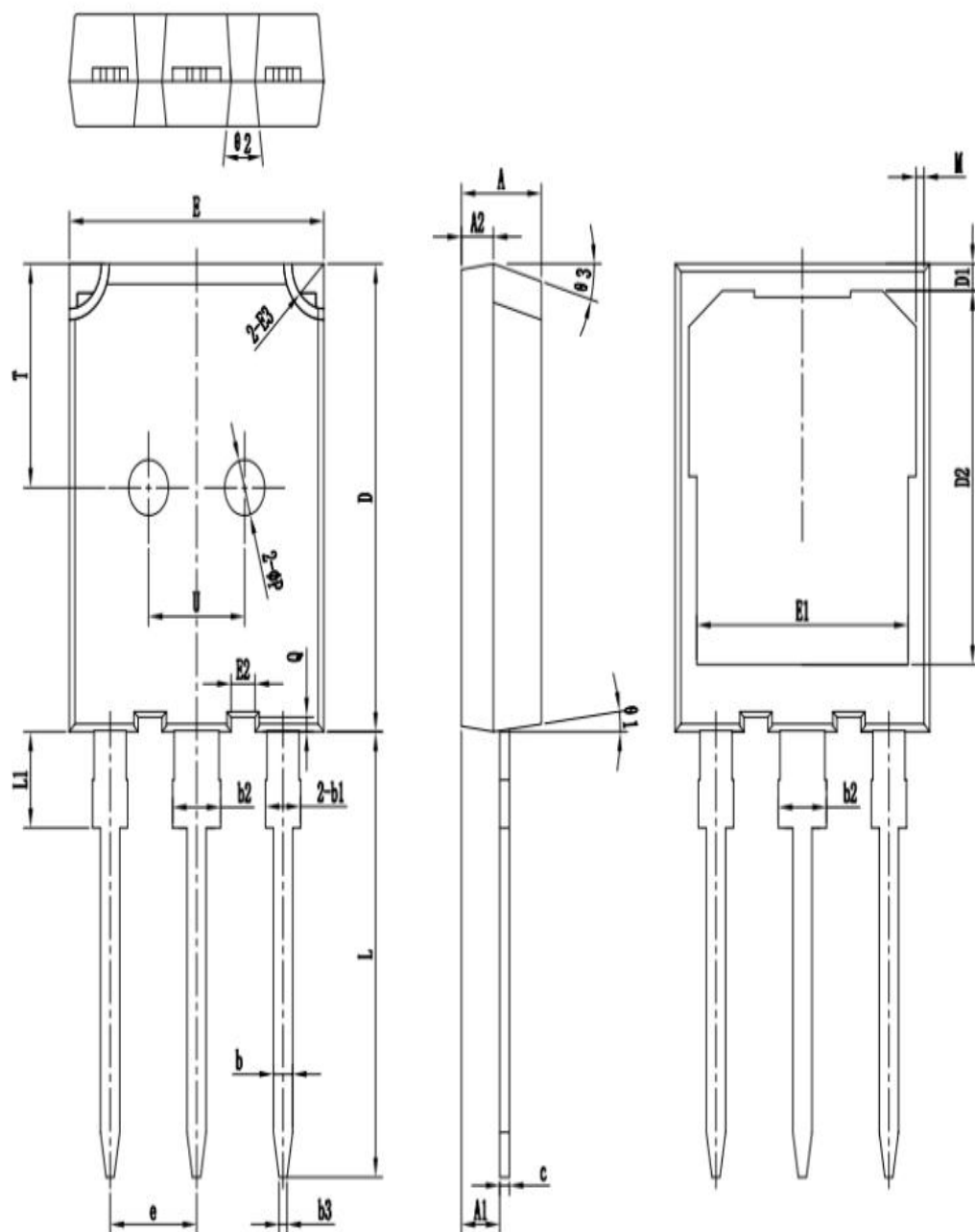


图 12. 开关损耗 二极管

Figure 12. Switching losses of Diode  
 $I_F=120A$ ,  $V_{CE}=600V$



Package outline drawing(TO-247PLUS-3 Unit: mm )



序号	单位:mm		
	MIN	NOM	MAX
ø4	4.90	5.00	5.10
ø4.1	2.31	2.41	2.51
A2	1.90	2.00	2.10
ø6	1.15	1.20	1.25
ø6.1	1.95	2.10	2.25
ø6.2	2.95	3.10	3.25
b3	0.45	0.60	0.75
ø6	0.55	0.60	0.68
ø6	20.90	21.00	21.10
D1	1.00	1.20	1.40
D2	15.25	16.55	16.85
ø6	15.70	15.80	15.90
E1	13.10	13.30	13.50
E2	1.25	1.45	1.65
E3	1.80	2.00	2.20
ø6	5.40	5.44	5.48
ø6	19.80	19.92	20.10
ø6.1	-	-	4.30
øP	2.30	2.50	2.70
Q	0.50	0.68	0.80
T	9.80	10.00	10.20
U	5.80	6.00	6.20
Ø1	5°	7°	9°
Ø2	13°	16°	19°
Ø3	13°	15°	17°

\*为关键管控尺寸

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